



Liu et al  
USSN 09/208,963  
Filed Dec. 10, 1998

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of )  
John Liu et al ) Examiner Harry D. Wilkins, III *#13*  
Serial No. 09/208,963 ) Group Art Unit 1742 *41*  
Filed December 10, 1998 ) Attorney Docket 97-2739 *20*  
For High Toughness Plate Alloy )  
for Aerospace Applications ) *1/28/01*

**Amendment**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on February 28, 2001.

*Charles Q. Buckwalter*  
Charles Q. Buckwalter, Reg. No. 32969  
Date of Signature: February 28, 2001

Assistant Commissioner for Patents  
Box RCE  
Washington, DC 20231

Sir:

The following is in response to the Office Action dated January 10, 2001.

**In the claims:**

In accordance with 37 CFR 1.121:

- (a) a marked form version of the amended claims is presented in the "Marked Claims" attached to this Amendment; and
- (b) a clean form version of the amended claims is presented below.

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